



Product Change Notification / SYST-21NXHZ132

Date:

13-Jan-2021

Product Category:

Radiation Hardness

PCN Type:

Document Change

Notification Subject:

Data Sheet - SAMRH71 Data Sheet

Affected CPNs:

[SYST-21NXHZ132_Affected_CPN_01132021.pdf](#)

[SYST-21NXHZ132_Affected_CPN_01132021.csv](#)

Notification Text:

SYST-21NXHZ132

Microchip has released a new Product Documents for the SAMRH71 Data Sheet of devices. If you are using one of these devices please read the document located at [SAMRH71 Data Sheet](#).

Notification Status: Final

Description of Change:

- 1) Added a new section 625 balls TFBGA Package
- 2) Updated the TFBGA625 section.
- 3) Added new table and figure for 625 TFBGA package.
- 4) Updated the Package Marking Information section.
- 5) Updated the following modules: TCMTHECC, FLEXRAMECC, MATRIX, HEFC, SUPC, RSTC, PMC, PIO, HEMC, HECC, HSMC, IP1553, SPW, XDMAC, and NIMC.

Impacts to Data Sheet: None

Reason for Change: To Improve Manufacturability

Change Implementation Status: Complete

Date Document Changes Effective: 13 Jan 2021

NOTE: Please be advised that this is a change to the document only the product has not been changed.

Markings to Distinguish Revised from Unrevised Devices: N/A

Attachments:

[SAMRH71 Data Sheet](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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